

L Number	Hits	Search Text	DB	Time stamp
1	669	156/\$.ccls. and (b adj stage\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 11:42
2	659	(156/\$.ccls. and (b adj stage\$3)) and (@ad<20011214)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:50
3	287	((156/\$.ccls. and (b adj stage\$3)) and (@ad<20011214)) and (chip or die or wafer or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 11:33
4	69	(b adj stage\$3) near (mixture or combination)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 11:58
5	17	(cure near (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (cure near (epoxy or (epoxy near imidazole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:44
6	0	2001083652.URPN.	USPAT	2003/03/06 12:29
7	194	(first and second) near cure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:34
8	3	((first and second) near cure) and (cure with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (cure with (epoxy or (epoxy near imidazole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:37
9	2644	156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:46
10	1186	(156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and cure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:47
11	576	(156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and (cure with (heat or temperature))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:49
12	569	((156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and (cure with (heat or temperature))) and (@ad<20011214)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:42
13	246	((156/\$.ccls. and (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl))) and (epoxy or (epoxy near imidazole))) and (cure with (heat or temperature))) and (@ad<20011214) and (chip or die or silicon or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:09
14	277	(dual adj cur\$3) and (chip or die or wafer or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:11

15	261	((dual adj cur\$3) and (chip or die or wafer or silicon)) and (@ad<20011214)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:18
16	181	((((dual adj cur\$3) and (chip or die or wafer or silicon)) and (@ad<20011214)) and (cur\$3 with (heat or temperature)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:25
17	7	((((dual adj cur\$3) and (chip or die or wafer or silicon)) and (@ad<20011214)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:29
18	82	cur\$ near ((filler or globule or pellet or particle)and (liquid or solvent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:32
19	83	cur\$3 near ((filler or globule or pellet or particle)and (liquid or solvent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:35
20	83	cur\$3 near ((filler or globule or pellet or particle) and (liquid or solvent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:35
21	7	(cur\$3 near ((filler or globule or pellet or particle)and (liquid or solvent))) and ((filler or globule or pellet or particle) near (liquid or solvent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:36
22	384	((((Liquid or solvent) and cure) with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (epoxy or (epoxy near imidazole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:41
23	60	((((Liquid or solvent) and cure) with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (epoxy or (epoxy near imidazole))) and ((underfill or adhesive) and (chip or die or wafer or silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:42
24	57	(((((Liquid or solvent) and cure) with (acrylic or (cycloaliphatic adj epoxy) or bismaleimide or (bismaleimide near (vinyl or styrenic or cinnamyl)))) and (epoxy or (epoxy near imidazole))) and ((underfill or adhesive) and (chip or die or wafer or silicon))) and (@ad<20011214)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:54
25	2328	(liquid near (mixture or combination)) and (dual or (first and second) near cure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:55
26	2246	((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:55
27	0	((((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)) and ((liquid and solvent) near cure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 14:07

28	0	"L29" and ((liquid and solvent) near cure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 14:13
29	0	((((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)) and ((liquid and solvent) near cure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 14:15
30	11	.(((liquid near (mixture or combination)) and (dual or (first and second) near cure) ) and (@ad<20011214)) and ((liquid and solvent) with cure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 14:15